



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20251016000.1

**Qualify TIEM and CDAT as an additional Assembly site for select devices
Change Notification / Sample Request**

Date: October 16, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20251016000.1**Attachment: 1****Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

| DEVICE | CUSTOMER PART NUMBER |
|----------------|----------------------|
| LM339PWR | LM339PWR |
| SN74LVC07APWR | NULL |
| ULN2003AIPWR | ULN2003AIPWR |
| CD74HC4051PWR | CD74HC4051PWR |
| SN74LV07APWRG3 | NULL |
| LM239PWR | NULL |
| SN74LV8T594PWR | NULL |
| LM339APWR | NULL |
| SN74LVC08APWR | NULL |
| SN74LVC125APWR | NULL |
| SN74LV164APWR | NULL |
| CD4504BPWR | NULL |
| TS3A5018PWR | TS3A5018PWR |
| SN74AHC594PWR | SN74AHC594PWR |
| SN74LV4051APWR | NULL |
| SN74LVC14APWR | NULL |
| SN74LV4052APWR | SN74LV4052APWR |
| SN74AHC125PWR | NULL |
| SN74LVC00APWR | NULL |
| CD74HC4052PWR | CD74HC4052PWR |
| LM2901PWR | LM2901PWR |
| CD4093BPWR | NULL |
| TLV9064IPWR | NULL |
| SN74LV8T165PWR | NULL |
| ULN2003APWR | ULN2003APWR |
| TCA9546APWR | TCA9546APWR |
| TLV9054IPWR | TLV9054IPWR |

Technical details of this Product Change follow on the next page(s).

| | | | |
|---|--|--|--------------------|
| PCN Number: | 20251016000.1 | PCN Date: | October 16, 2025 |
| Title: | Qualify TIEM and CDAT as an additional Assembly sites for select devices | | |
| Customer Contact: | Change Management team | Dept: | Quality Services |
| Proposed 1st Ship Date: | January 14, 2026 | Sample requests accepted until: | December 15, 2025* |

*Sample requests received after December 15, 2025 will not be supported.

Change Type:

| | | |
|--|---|--|
| <input checked="" type="checkbox"/> Assembly Site | <input type="checkbox"/> Design | <input type="checkbox"/> Wafer Bump Material |
| <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Data Sheet | <input type="checkbox"/> Wafer Bump Process |
| <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Part number change | <input type="checkbox"/> Wafer Fab Site |
| <input type="checkbox"/> Mechanical Specification | <input type="checkbox"/> Test Site | <input type="checkbox"/> Wafer Fab Material |
| <input checked="" type="checkbox"/> Packing/Shipping/ Labeling | <input type="checkbox"/> Test Process | <input type="checkbox"/> Wafer Fab Process |

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of TI Melaka (TIEM) and TI Chengdu (CDAT) as an additional Assembly sites for the list of devices shown below. Material differences between sites are as follows.

| | Current site | | Additional Sites |
|----------------|---------------------|------------|-------------------------|
| Assembly site | TFME* | MLA | TIEM/CDAT |
| Mount compound | SID#A-03 | 4147858 | 4211470 |
| Mold compound | SID#R-31 | 4211471 | 4228573 |
| Lead finish | Matte Sn | NiPdAu | Matte Sn |

*Applicable for SN74LV07APWRG3

Reason for Change:

Continuity of supply.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None.

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

| RoHS | REACH | Green Status | IEC 62474 |
|---|---|---|---|
| <input checked="" type="checkbox"/> No Change |

Changes to product identification resulting from this PCN:

Assembly Site Information:

| Assembly Site | Assembly Site Origin (22L) | Assembly Country Code (23L) | Assembly City |
|---------------|----------------------------|-----------------------------|----------------|
| TFME | NFM | CHN | Chongchuan |
| MLA | MLA | MYS | Kuala Lumpur |
| CDAT | CDA | CHN | Chengdu |
| TIEM | CU6 | MYS | Melaka |

Sample product shipping label (not actual product label)



(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CO:USA
(22L) ASO: MLA (23L) AC0: MYS

Product Affected:

| | | | |
|---------------|----------------|----------------|--------------|
| AM26C31IPWR | LM339PWR | SN74LV8T594PWR | TLV9054IPWR |
| CD4093BPWR | SN74AHC125PWR | SN74LVC00APWR | TLV9064IPWR |
| CD4504BPWR | SN74AHC594PWR | SN74LVC07APWR | TS3A5018PWR |
| CD74HC4051PWR | SN74LV07APWRG3 | SN74LVC08APWR | ULN2003AIPWR |
| CD74HC4052PWR | SN74LV164APWR | SN74LVC125APWR | ULN2003APWR |
| LM239PWR | SN74LV4051APWR | SN74LVC14APWR | |
| LM2901PWR | SN74LV4052APWR | TCA9546APWR | |
| LM339APWR | SN74LV8T165PWR | TLV2374IPWR | |

Qualification Report (TIEM)

Approve Date 23-January-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type | # | Test Name | Condition | Duration | Qual Device: AM26C31IPWR | Qual Device: SN74HC14PWR | QBS Reference: LM5576QMH/NOPB |
|-------|----|-------------------------------|--|------------|-----------------------------|-----------------------------|----------------------------------|
| HAST | A2 | Biased HAST | 130C/85%RH | 96 Hours | - | - | 3/231/0 |
| UHAST | A3 | Autoclave | 121C/15psig | 96 Hours | - | 3/231/0 | - |
| UHAST | A3 | Unbiased HAST | 130C/85%RH | 96 Hours | - | - | 3/231/0 |
| TC | A4 | Temperature Cycle | -65C/150C | 500 Cycles | 3/231/0 | 3/231/0 | 3/231/0 |
| HTSL | A6 | High Temperature Storage Life | 150C | 1000 Hours | - | - | 3/135/0 |
| HTOL | B1 | Life Test | 125C | 1000 Hours | - | - | 1/77/0 |
| SD | C3 | PB-Free Solderability | Precondition w/155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder, | - | 3/66/0 | 3/66/0 | 1/30/0 |
| PD | C4 | Physical Dimensions | Cpk>1.67 | - | 3/30/0 | 3/30/0 | 3/30/0 |

QBS: Qual By Similarity, also known as Generic Data

Qual Device AM26C31IPWR is qualified at MSL1 260C

Qual Device SN74HC14PWR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2311-009

Qualification Report (TIEM)

Approve Date 30-June-2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type | # | Test Name | Condition | Duration | Qual Device: <u>LMP7704MT/NOPB</u> | Qual Device: <u>LMH0346MH/NOPB</u> | QBS Reference: <u>LM5576QMH/NOPB</u> | QBS Reference: <u>LM5118Q1MH/NOPB</u> |
|-------|----|-------------------------------|--|------------|---------------------------------------|---------------------------------------|---|--|
| HAST | A2 | Biased HAST | 130C/85%RH | 96 Hours | - | - | 3/231/0 | - |
| UHAST | A3 | Autoclave/UHAST | 121C/15psig Or 130C/85%RH | 96 Hours | 3/231/0 | - | 3/231/0 | 3/231/0 |
| TC | A4 | Temperature Cycle | -65C/150C | 500 Cycles | 3/231/0 | 3/231/0 | 3/231/0 | 3/231/0 |
| HTSL | A6 | High Temperature Storage Life | 170C | 420 Hours | 3/231/0 | - | 3/135/0 | 3/135/0 |
| HTOL | B1 | Life Test | 125C | 1000 Hours | - | - | 1/77/0 | - |
| SD | C3 | PB-Free Solderability | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes). PB-Free Solder; | - | 3/66/0 | 3/66/0 | - | - |
| FTY | E6 | Final Test Yield | - | - | 3/3/0 | 3/3/0 | - | - |

QBS: Qual By Similarity, also known as Generic Data

Qual Device LMP7704MT/NOPB is qualified at MSL1 260C

Qual Device LMH0346MH/NOPB is qualified at MSL3 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2401-019

Qualification Report (CDAT)

Approve Date 27-August-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type | # | Test Name | Condition | Duration | Qual Device: SN74AXC4T245PWR | Qual Device: SN74HCS08PWR | Qual Device: TMUX1308PWR | Qual Device: MAX202IPWR | QBS Reference: TMUX1308QPWRQ1 | OBS Reference: LMP8601EDRQ1 |
|-------|----|-------------------------------|--|------------|------------------------------|---------------------------|--------------------------|-------------------------|-------------------------------|-----------------------------|
| HAST | A2 | Biased HAST | 130C/85%RH | 96 Hours | - | - | - | - | 1/77/0* | 3/231/0* |
| UHAST | A3 | Unbiased HAST | 130C/85%RH | 96 Hours | - | - | - | - | 3/231/0 | - |
| TC | A4 | Temperature Cycle | -65C/150C | 500 Cycles | - | - | - | - | 3/231/0 | - |
| HTSL | A6 | High Temperature Storage Life | 170C | 420 Hours | - | - | - | - | 3/231/0 | - |
| SD | C3 | PB-Free Solderability | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder; | - | - | - | - | - | 3/66/0 | - |
| MQ | | Assembly MQ | Per site specification | - | 1/Pass | 1/Pass | 1/Pass | 3/Pass | 3/Pass | - |

QBS: Qual By Similarity, also known as Generic Data

Qual Device SN74AXC4T245PWR is qualified at MSL1 260C

Qual Device SN74HCS08PWR is qualified at MSL1 260C

Qual Device TMUX1308PWR is qualified at MSL1 260C

Qual Device MAX202IPWR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
TI Qualification ID: R-CHG-2402-077

Qualification Report (CDAT)

Approve Date 13-November-2023

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

| Type | # | Test Name | Condition | Duration | Qual Device: TPS35JE35JADDSER | QBS Process/Product Reference: TPS35AA38AGADDFRQ1 | QBS Process Reference: PCM6260QRTVRQ1 | QBS Package Reference: TPS37A010122DSKRQ1 | QBS Package Reference: TPM117AIDRVR |
|-------|----|-------------------------------|---|------------|----------------------------------|--|--|--|--|
| HAST | A2 | Biased HAST | 130C/85%RH | 96 Hours | - | 1/77/0 | 3/231/0 | 1/77/0 | 3/231/0 |
| UHAST | A3 | Unbiased HAST | 130C/85%RH | 96 Hours | - | 1/77/0 | 3/231/0 | 3/231/0 | 3/231/0 |
| TC | A4 | Temperature Cycle | -65C/150C | 500 Cycles | - | 1/77/0 | - | - | 3/231/0 |
| HTSL | A6 | High Temperature Storage Life | 150C | 1000 Hours | - | 1/77/0 | 3/135/0 | 3/135/0 | 3/231/0 |
| HTOL | B1 | Life Test | 125C | 1000 Hours | - | 1/77/0 | 3/231/0 | - | - |
| HTOL | B1 | Life Test | 150C | 300 Hours | - | - | - | - | 3/231/0 |
| ELFR | B2 | Early Life Failure Rate | 125C | 48 Hours | - | - | 3/2400/0 | - | - |
| SD | C3 | PB Solderability | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes) | - | - | 1/15/0 | 1/15/0 | - | - |
| SD | C3 | PB-Free Solderability | Precondition w.155C Dry Bake (4 hrs +/- 15 minutes) | - | - | 1/15/0 | 1/15/0 | - | - |
| PD | C4 | Physical Dimensions | Cpk>1.67 | - | - | 1/10/0 | 3/30/0 | 3/30/0 | - |
| ESD | E2 | ESD CDM | - | 250 Volts | 1/3/0 | - | - | - | 1/3/0 |
| ESD | E2 | ESD HBM | - | 1000 Volts | 1/3/0 | - | - | - | 1/3/0 |
| LU | E4 | Latch-Up | Per JESD78 | - | 1/3/0 | 1/6/0 | 1/6/0 | - | 1/3/0 |
| CHAR | E5 | Electrical Characterization | Per Datasheet Parameters | - | 1/30/0 | 3/90/0 | 3/90/0 | - | 3/90/0 |

QBS: Qual By Similarity

Qual Device TPS35JE35JADDSER is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-NPD-2310-038

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.